

Title (en)  
METHOD AND DEVICE FOR CONNECTING CHIPS

Title (de)  
VERFAHREN UND EINRICHTUNG ZUM VERBINDEN VON CHIPS

Title (fr)  
PROCEDE ET DISPOSITIF DE CONNEXION DE PUCES

Publication  
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Application  
**EP 04805792 A 20041028**

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• FR 0350774 A 20031103

Abstract (en)  
[origin: WO2005045934A2] The invention relates to an electronic device comprising: a circuit (20, 50) having a first and second face, said first face being fitted with electrical connecting means (22, 53); a transfer element (24, 50) comprising a first and second face, assembled with its first face placed against the second face of the active element, and comprising electrical connecting means (26, 62) on its second face, and; a connection (32, 56) between the electrical connecting means of the active element and those of the transfer element.

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IPC 8 full level  
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**H01L 23/3185** (2013.01 - EP US); **H01L 24/81** (2013.01 - EP US); **H01L 24/92** (2013.01 - EP US); **H01L 24/96** (2013.01 - EP US); **H01L 25/18** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/4824** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2224/81801** (2013.01 - EP US); **H01L 2224/83001** (2013.01 - EP US); **H01L 2224/85001** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01061** (2013.01 - EP US); **H01L 2924/01077** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/10253** (2013.01 - EP US); **H01L 2924/12041** (2013.01 - EP US); **H10F 39/15** (2025.01 - EP US)

C-Set (source: EP US)  
1. **H01L 2224/48091 + H01L 2924/00014**  
2. **H01L 2924/10253 + H01L 2924/00**  
3. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00**  
4. **H01L 2924/12041 + H01L 2924/00**  
5. **H01L 2924/00014 + H01L 2224/45099**  
6. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**

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